L Number	Hits	S arch Text	DB	Time stamp
1	751	(((Core and clad\$4)) and wave\$guide and	USPAT;	2003/02/12
-		(mask or hard4mask r etch\$ mask)) and	US-PGPUB;	08:53
		(resist r ph t resist)	DERWENT	
	164	((((Core and clad\$4)) and wave\$guide and	USPAT;	2003/02/12
3	104	, ,,,,	•	
		(mask or hard4mask or etch\$ mask)) and	US-PGPUB;	11:08
	1	(resist or photoresist)) and (Cr or chrome or	DERWENT	
		chromium)		
5	451	((((Core and clad\$4)) and wave\$guide and	USPAT;	2003/02/12
		(mask or hard4mask or etch\$ mask)) and	US-PGPUB;	10:35
		(resist or photoresist)) and \$4align\$4	DERWENT	
8	97	(((((Core and clad\$4)) and wave\$guide and	USPAT;	2003/02/12
		(mask or hard4mask or etch\$ mask)) and	US-PGPUB;	11:09
		(resist or photoresist)) and (Cr or chrome or	DERWENT	
		chromium)) and (align\$3 or self\$align\$3)		
	95	((((((Core and clad\$4)) and wave\$guide and	USPAT;	2003/02/12
•	33	(mask or hard4mask or etch\$ mask)) and	i -	11:10
	ĺ		US-PGPUB;	11:10
		(resist or photoresist)) and (Cr or chrome or	DERWENT	
		_chromium)) and (align\$3-or self\$align\$3)) and _		
		(quartz or silica or SiO2 or Glass)		
· -	989	(430/321).CCLS.	USPAT;	2003/02/10
			US-PGPUB;	11:31
			DERWENT	
•	143	(216/25,26).CCLS.	USPAT;	2003/02/10
		(200,20,000,000	US-PGPUB;	15:12
			DERWENT	
-	882	Wave\$guide and micro\$machin\$4		2003/02/10
	002	waveşguide and microşmacninş4	USPAT;	
			US-PGPUB;	15:30
			DERWENT	
-	580	(Wave\$guide and micro\$machin\$4) and	USPAT;	2003/02/10
		etch\$4	US-PGPUB;	15:15
			DERWENT	
-	35	(Wave\$guide and micro\$machin\$4).clm.	USPAT;	2003/02/10
			US-PGPUB;	16:52
			DERWENT	
	49	(Wave\$guide and micro\$machin\$4) and	USPAT;	2003/02/10
-		self\$align\$3	US-PGPUB;	15:30
			DERWENT	
	246	(Movetavide and misustancehints) and		2002/02/40
-	218	(Wave\$guide and micro\$machin\$4) and	USPAT;	2003/02/10
	1	((Core and clad\$4))	US-PGPUB;	16:43
	1		DERWENT	
•	125	(65/385).CCLS.	USPAT;	2003/02/10
			US-PGPUB;	16:50
			DERWENT	
•	101	(65/429).CCLS.	USPAT;	2003/02/10
		` '	US-PGPUB;	17:40
	-		DERWENT	
-	1095	(385/88).CCLS.	USPAT;	2003/02/10
	1095	(303/00).UCL3.		1
			US-PGPUB;	16:52
			DERWENT	
•	19	(Wav \$guide and micr \$machin\$4) and	USPAT;	2003/02/10
	-	((385/88).CCLS.)	US-PGPUB;	16:59
	1		DERWENT	

			•	
•	754	(385/129).CCLS.	USPAT;	2003/02/10
			US-PGPUB;	16:59
			DERWENT	
•	19	(Wave\$guid and micr \$machin\$4) and	USPAT;	2003/02/10
		((385/129).CCLS.)	US-PGPUB;	17:02
			DERWENT	
•	926	(385/147).CCLS.	USPAT;	2003/02/10
			US-PGPUB;	17:02
			DERWENT	
•	4	(Wave\$guide and micro\$machin\$4) and	USPAT;	2003/02/10
		((385/147).CCLS.)	US-PGPUB;	17:02
			DERWENT	
•	250	((Core and clad\$4)) and ((385/88).CCLS.)	USPAT;	2003/02/10
			US-PGPUB;	17:41
			DERWENT	
•	27947	(Core and clad\$4)	USPAT;	2003/02/11
		·	US-PGPUB;	18:06
			DERWENT	
-	67672	wave\$guide	USPAT;	2003/02/11
			_US-PGPUB;=	=18:07
	and the second second second		DERWENT	
•	464166	mask or hard4mask or etch\$ mask	USPAT;	2003/02/11
			US-PGPUB;	18:08
			DERWENT	
-	3007	((Core and clad\$4)) and wave\$guide and	USPAT;	2003/02/11
		(mask or hard4mask or etch\$ mask)	US-PGPUB;	18:09
			DERWENT	
-	310275	resist or photoresist	USPAT;	2003/02/11
			US-PGPUB;	18:10
			DERWENT	